

#### **Objectives**

At the end of this Unit, the student should:

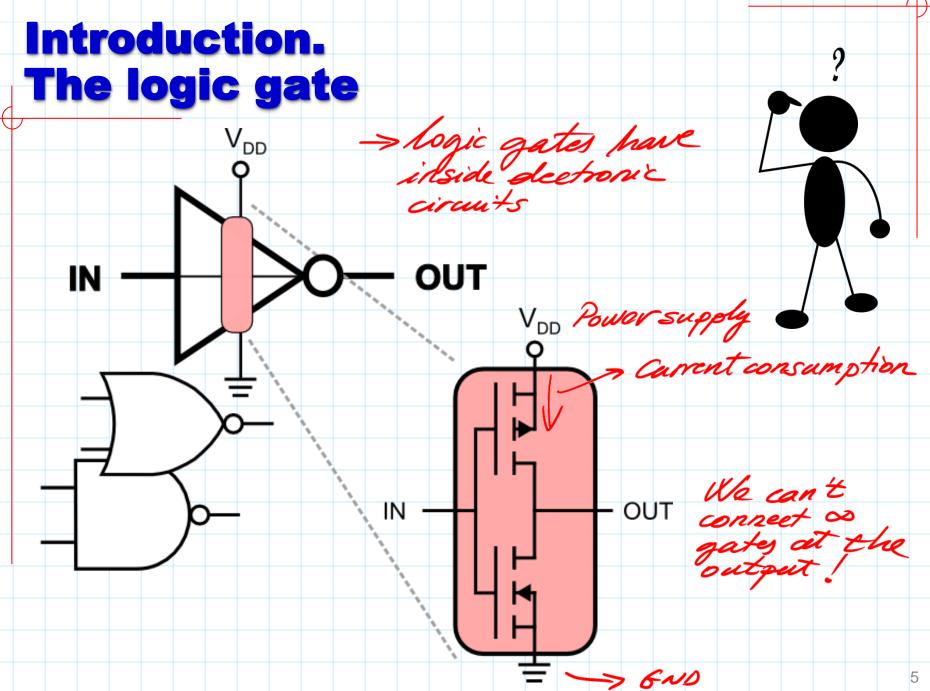
- Understand the definition of the states of logic gates.
- Know and understand the behavior of input and output terminals of a logic circuit.
- Understand the characteristic parameters of a logic gate, both at electrical and temporal level.
- Understand the problem of interconnecting integrated logic circuits with different technologies, solving some case studies of interconnection.
- Know the different TTL subfamilies

#### **Bibliography**

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- 2. A.R. Hambley. "Electrónica" (2ª ed., 2001). Prentice Hall. Capítulo 6.
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- 5. R. Tokheim. "Electrónica digital, principios y aplicaciones" (7ª ed., 2008). Mcgraw-hill.
- 6. A.P. Malvino. "Principios y aplicaciones digitales" (1988). Marcombo.

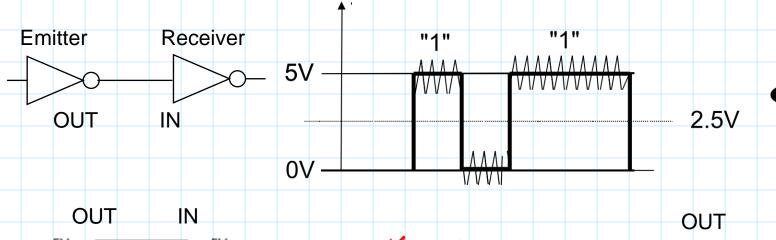
#### **Contents**

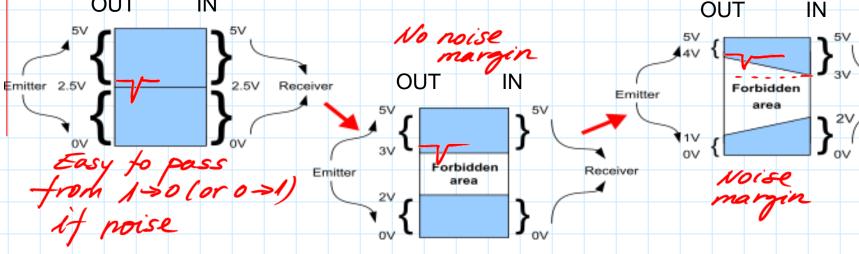
- 1. Introduction
- 2. Types of outputs and inputs
- 3. Characteristic parameters
- 4. Interconnection of digital elements
- 5. TTL family and subfamilies



### Introduction. Abstraction of "0" and "1"

Logic levels "0" and "1" are not fixed voltage values, each one is associated with a different voltage range





Receiver

#### Introduction. What is a logic family?

#### Logic family

- Set of functional elements (logic gates, biestables, decoders, counters, ...) with the same base circuit and the same manufacturing technology
- Electric compatibility, direct interconnection all family members understand themselves

CMOS: thigh integration density

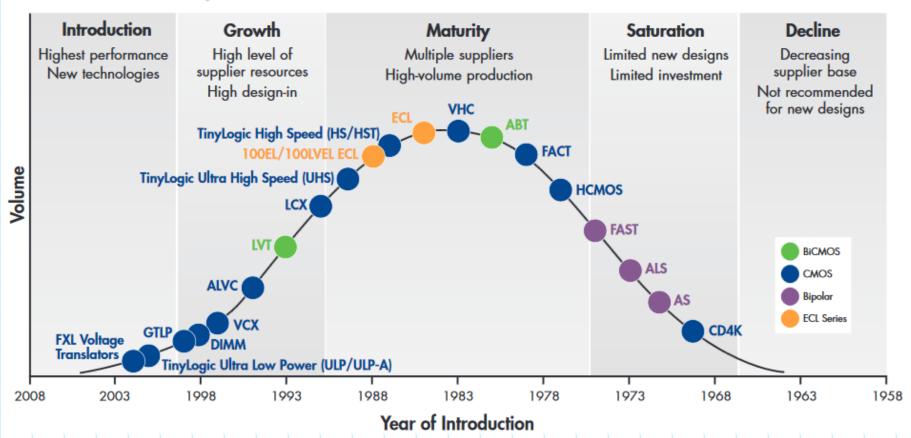
#### Main logic families

- Bipolar
  - Transistor Transistor Logic (TTL, LSTTL, STTL, ASTTL, ALSTTL, FAST)

     Standard
  - Emitter Coupled Logic (ECL) (old)
- MOS
  - PMOS, NMOS
  - CMOS
  - Pass-transistor CMOS
  - Dynamic CMOS (Domino)
- High Output Current High Speed BiCMOS (Bipolar- CMOS)
- Ga As (Gallium Arsenide)

# Introduction. Logic families evolution

#### Product Life Cycle



Source: <a href="https://www.fairchildsemi.com/collateral/Logic-Selection-Guide.pdf">https://www.fairchildsemi.com/collateral/Logic-Selection-Guide.pdf</a> (2008)

# Introduction. Integration scales

**SSI** (Small Scale of Integration): up to 10 gates (simple gates, flip-flops)

**MSI** (Medium Scale of Integration): 10 to 100 gates (*decoders, multiplexers, adders, counters, registers, ...)* 

**LSI** (Large Scale of Integration): 100 to 1000 gates (*microprocessors* (8bits), memories, ...)

(Memories, microprocessors and big PLDs) Normaly this is

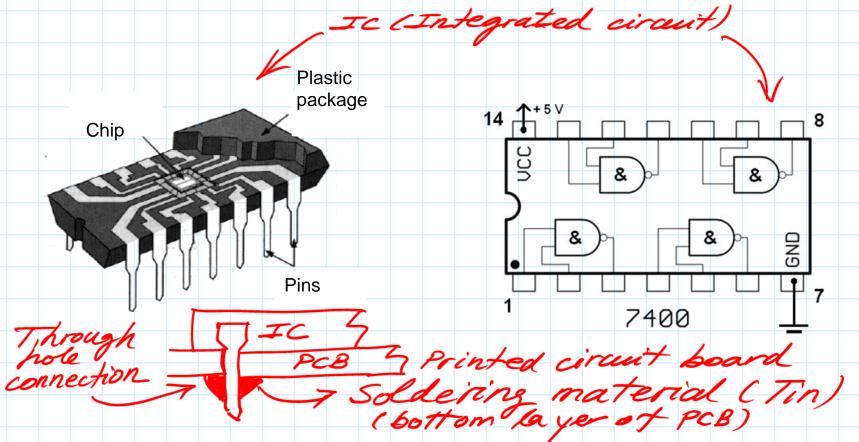
**ULSI** (Ultra Large Scale of Integration): more than 100K gates (microprocessors (32+), FPGA, microcontrollers, SoC...

GSI: (Giga Scale of Integration). More than 1M gates.

Today: 1 billion transistor (chip or more Approx. Conversion Factor: For CMOS technology: 6 transistors/gate

# Introduction Packages

To place the integrated circuit in an electronic system built on a printed circuit board (eg. a motherboard of a modern computer) is necessary to insert the chip in a protective shell called package.



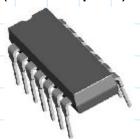
# Introduction Packages

#### Soldered in upper layer 5MD: Surface Mount Device

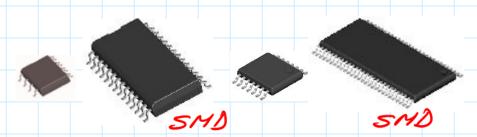
Packaging technology has followed a development parallel to the integration density

Dual-In-Line Package (DIP ó DIL) (until 80 pins)

Plastic Leaded Chip Carrier (PLCC) (until 84 pins) Small Outline Integrated Circuit (SOIC) / Shrink Small Outline Package (SSOP), Thin Shrink Small Outline Package (TSSOP)







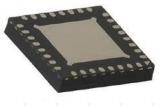
Quad Flat Pack (QFP)
Thin Quad Flat Package
(TQFP)
(until 300 pins)

Pin Grid Array (PGA) (until 400 pins)

Ball Grid Array (BGA) Quad Flat No-Lead (greater pin number) Plastic Package (QFN)

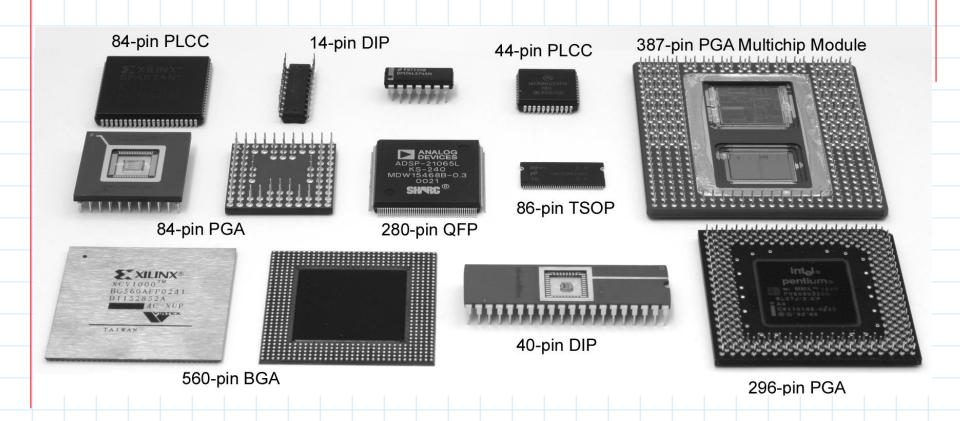






5MD

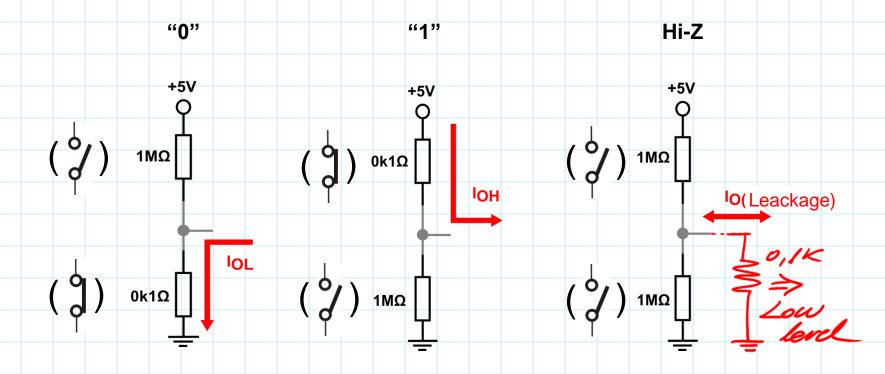
# Introduction Packages



### Output types State of one terminal

One output can have 3 different states: "0", "1" and Hi-Z (or "Z")

- Hi-Z: High impedance output; voltage established without force
- "0", "1": Low impedance outputs; voltage established with force



**IBIS model.** I/O Buffer Information Specification. Employed by manufacturers to offer a model of their circuits hiding its internal design (SPICE). I/V tables and V/t tables.

#### **Output types**

Output types in terms of possible output values:

"0" and "1." Standard Output, Totem-Pole.

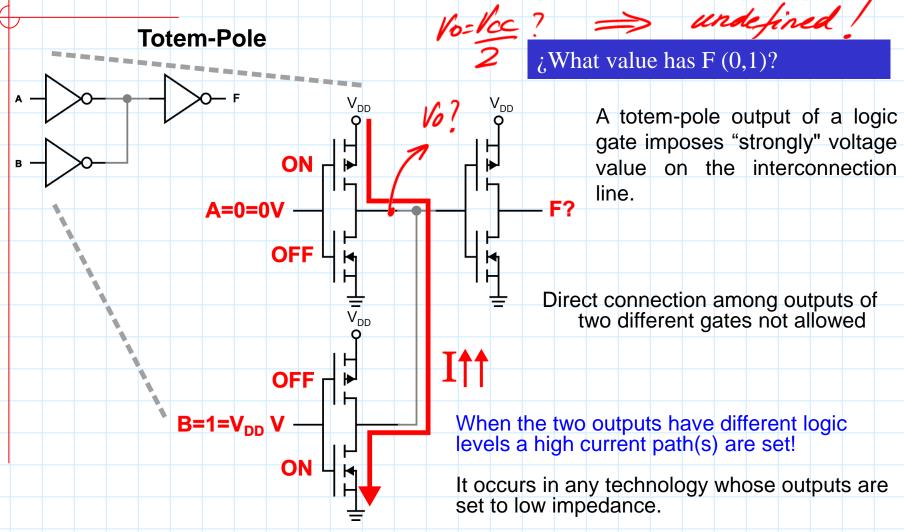
"0" and Z. Open collector and open drain.

Used in processor interrupt lines, serial communication buses such as I2C, lines of digital I/O in  $\mu$ Controlers

"0", "1" and "Z". Tri-state outputs

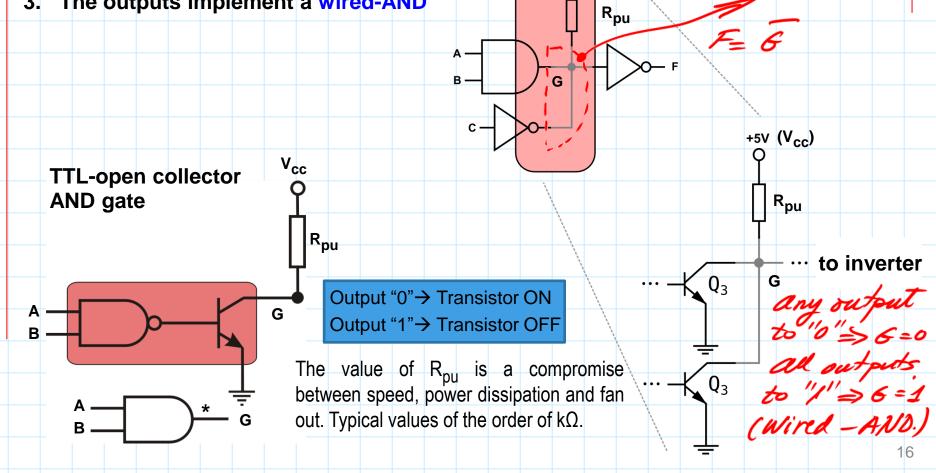
Used on data buses in a single-processor computers, and on address buses in systems with multiple processors.

# Output types. Totem-pole/Standard ("0" and "1") Various? => undefined!



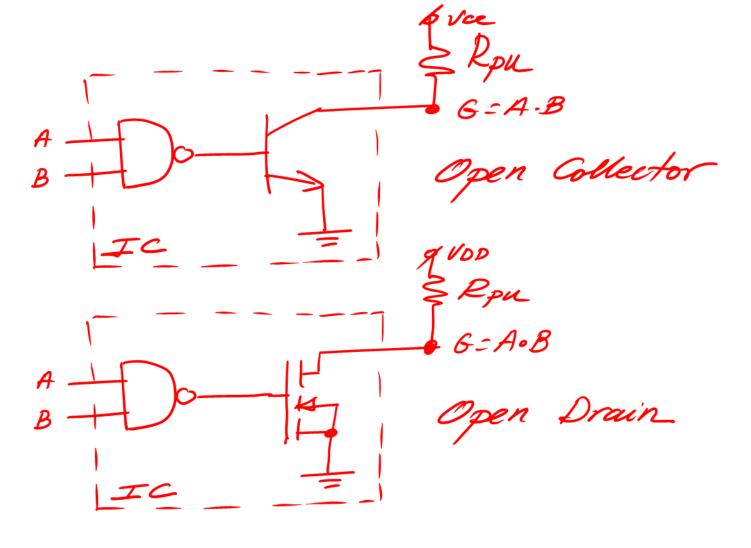
# Output types. Open collector/drain ("0" and "Z")

- Allows the wired-logic
- It is necessary an external "Pull-up"resistor (R<sub>pu</sub>), to obtain the High level
- The outputs implement a wired-AND



What is the value of F(1,0,1)?

6= (A.B) · C



Ppu is outside IC (Integrated circuit)

# Output types Open collector/drain ("0" and Z)

Used in the interruption lines of computers

Open Collector/Drain outputs IntR0 E/S<sub>1</sub> E/S<sub>2</sub> IntR1 **UCP**  $E/S_5$ E/S<sub>6</sub> E/S<sub>4</sub> IntR2 IntR3 E/S<sub>7</sub> QWERT E/S8 ASDFG